High Voltage Transistors

NPN Silicon

Features

• Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage MPSA43 MPSA42	V _{CEO}	200 300	Vdc
Collector - Base Voltage MPSA43 MPSA42	V _{CBO}	200 300	Vdc
Emitter - Base Voltage	V _{EBO}	6.0	Vdc
Collector Current - Continuous	I _C	500	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	625 5.0	mW mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	−55 to +150	°C

THERMAL CHARACTERISTICS

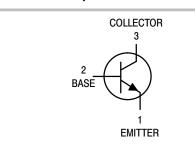
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/mW
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	83.3	°C/mW

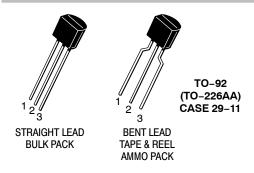
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



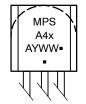
ON Semiconductor®

http://onsemi.com





MARKING DIAGRAM



x = 2 or 3
A = Assembly Location
Y = Year
WW = Work Week
■ Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS		1	1	JI.	
Collector – Emitter Breakdown Voltage (Note 1) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	MPSA42 MPSA43	V _{(BR)CEO}	300 200	<u>-</u>	Vdc
Collector – Base Breakdown Voltage (I_C = 100 μ Adc, I_E = 0)	MPSA42 MPSA43	V _{(BR)CBO}	300 200	_ _	Vdc
Emitter – Base Breakdown Voltage ($I_E = 100 \mu Adc, I_C = 0$)		V _{(BR)EBO}	6.0	-	Vdc
Collector Cutoff Current $(V_{CB} = 200 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 160 \text{ Vdc}, I_E = 0)$	MPSA42 MPSA43	Ісво	_ _	0.1 0.1	μAdc
Emitter Cutoff Current $(V_{EB} = 6.0 \text{ Vdc}, I_{C} = 0)$ $(V_{EB} = 4.0 \text{ Vdc}, I_{C} = 0)$	MPSA42 MPSA43	I _{EBO}	_ _	0.1 0.1	μAdc
ON CHARACTERISTICS (Note 1)					
DC Current Gain $ \begin{aligned} &(I_C=1.0 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ &(I_C=10 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \\ &(I_C=30 \text{ mAdc, } V_{CE}=10 \text{ Vdc}) \end{aligned} $		h _{FE}	25 40 40	- - -	-
Collector – Emitter Saturation Voltage ($I_C = 20 \text{ mAdc}$, $I_B = 2.0 \text{ mAdc}$)	MPSA42 MPSA43	V _{CE(sat)}	- -	0.5 0.4	Vdc
Base–Emitter Saturation Voltage ($I_C = 20 \text{ mAdc}$, $I_B = 2.0 \text{ mAdc}$)		V _{BE(sat)}	-	0.9	Vdc
SMALL-SIGNAL CHARACTERISTICS		1	•	•	•
Current – Gain – Bandwidth Product (I _C = 10 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)		f _T	50	_	MHz
Collector–Base Capacitance (V _{CB} = 20 Vdc, I _E = 0, f = 1.0 MHz)	MPSA42 MPSA43	C _{cb}	_ _	3.0 4.0	pF

^{1.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

ORDERING INFORMATION

Device	Package	Shipping [†]
MPSA42G	TO-92 (Pb-Free)	5000 Units / Box
MPSA42RL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
MPSA42RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
MPSA42RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA42RLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA42ZL1G	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA43RLRA	TO-92	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

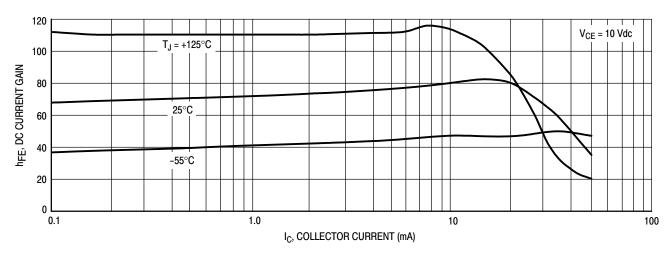


Figure 1. DC Current Gain

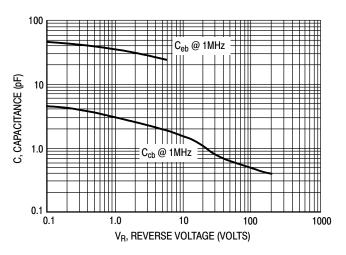


Figure 2. Capacitance

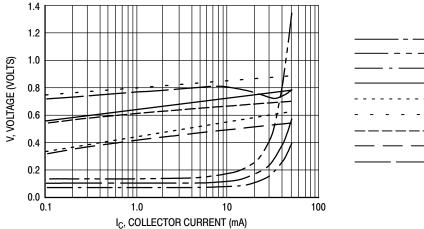
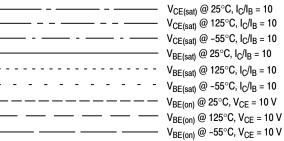
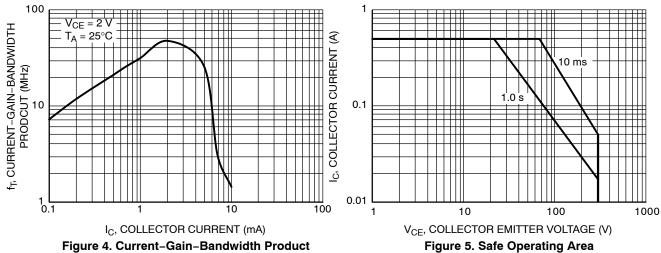


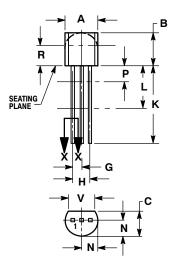
Figure 3. "ON" Voltages





PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 **ISSUE AM**



STRAIGHT LEAD **BULK PACK**







NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 CONTOUR OF PACKAGE BEYOND DIMENSION R
- IS UNCONTROLLED.
 LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

STYLE 1: STYLE 14: PIN 1. EMITTER PIN 1. EMITTER BASE 2. COLLECTOR COLLECTOR BASE

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
٧	3.43		

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and are registered raderians of semiconductor components industries, ILC (ScittLC) science (ScittLC). ScittLC reserves the right to make a relargest without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

Т SEATING PLANE

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative